

Product Summary

BV_{DSS}	$R_{DS(ON)}$ Max	I_D $T_A = +25^\circ C$
-60V	48m Ω @ $V_{GS} = -10V$	-5.2A
	60m Ω @ $V_{GS} = -4.5V$	-4.7A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

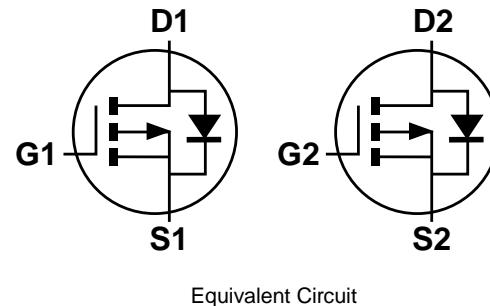
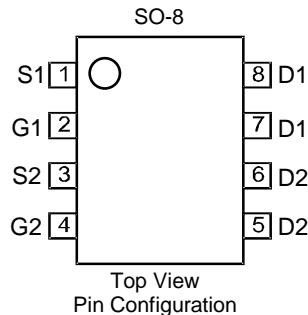
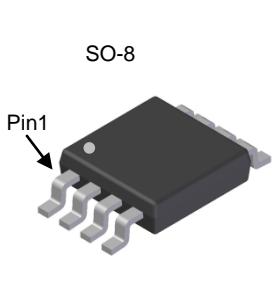
- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

- Rated to +175°C – ideal for high ambient temperature environments
- 100% Unclamped Inductive Switching – ensures more reliable and robust end application
- Low $R_{DS(ON)}$ – minimises power losses
- Low Q_g – minimises switching losses
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.076 grams (Approximate)



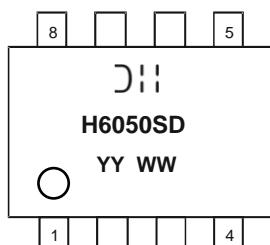
Ordering Information (Note 5)

Part Number	Case	Packaging
DMPH6050SSDQ-13	SO-8	2500 / Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



DII = Manufacturer's Marking
 H6050SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 16 = 2016)
 WW = Week (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	-60	V
Gate-Source Voltage			V_{GSS}	± 20	V
Continuous Drain Current (Note 7) $V_{GS} = -10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +100^\circ\text{C}$	I_D	-5.2 -3.7	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)			I_{DM}	-35	A
Maximum Continuous Body Diode Forward Current (Note 7)			I_S	-2.0	A
Avalanche Current (Note 8) $L = 0.1\text{mH}$			I_{AS}	-25	A
Avalanche Energy (Note 8) $L = 0.1\text{mH}$			E_{AS}	33	mJ

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	1.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	103	°C/W
	$t < 10\text{s}$		64	
Total Power Dissipation (Note 7)	$T_A = +25^\circ\text{C}$	P_D	2.0	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady state	$R_{\theta JA}$	75	°C/W
	$t < 10\text{s}$		47	
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	13	
Operating and Storage Temperature Range	T_J, T_{STG}		-55 to +175	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	-60	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	-1	μA	$V_{DS} = -60\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	-1.0	—	-3.0	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	34	48	$\text{m}\Omega$	$V_{GS} = -10\text{V}, I_D = -5\text{A}$
			44	60		$V_{GS} = -4.5\text{V}, I_D = -4\text{A}$
Diode Forward Voltage	V_{SD}	—	-0.7	-1.2	V	$V_{GS} = 0\text{V}, I_S = -1\text{A}$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	1525	—	pF	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	90	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	70	—	pF	
Gate Resistance	R_g	—	16	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = -4.5\text{V}$)	Q_g	—	14.5	—	nC	$V_{DS} = -30\text{V}, I_D = -5\text{A}$
Total Gate Charge ($V_{GS} = -10\text{V}$)	Q_g	—	30.6	—	nC	
Gate-Source Charge	Q_{gs}	—	4.9	—	nC	
Gate-Drain Charge	Q_{gd}	—	5.2	—	nC	
Turn-On Delay Time	$t_{D(\text{ON})}$	—	5.3	—	ns	$V_{GS} = -10\text{V}, V_{DS} = -30\text{V}, R_g = 3\Omega, I_D = -5\text{A}$
Turn-On Rise Time	t_R	—	15.4	—	ns	
Turn-Off Delay Time	$t_{D(\text{OFF})}$	—	79.2	—	ns	
Turn-Off Fall Time	t_F	—	45.3	—	ns	
Body Diode Reverse Recovery Time	t_{RR}	—	15.2	—	ns	$I_F = -5\text{A}, di/dt = -100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{RR}	—	9.3	—	nC	$I_F = -5\text{A}, di/dt = -100\text{A}/\mu\text{s}$

Notes:

6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
9. Short duration pulse test used to minimize self-heating effect.
10. Guaranteed by design. Not subject to product testing.

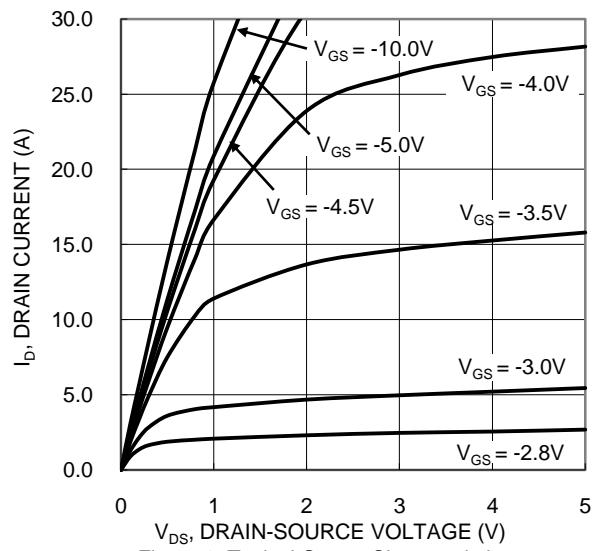


Figure 1. Typical Output Characteristic

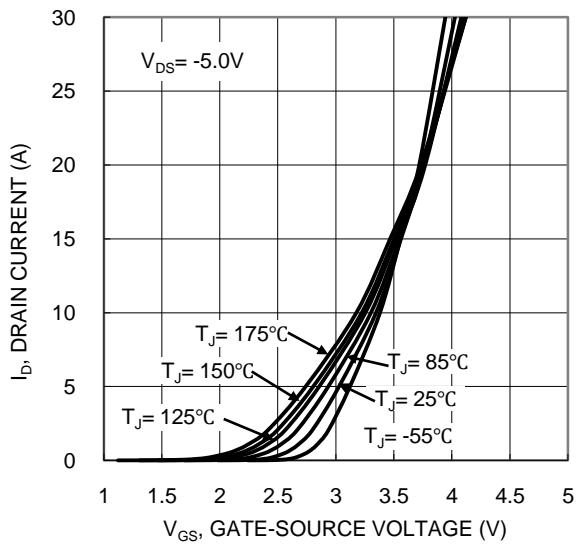


Figure 2. Typical Transfer Characteristic

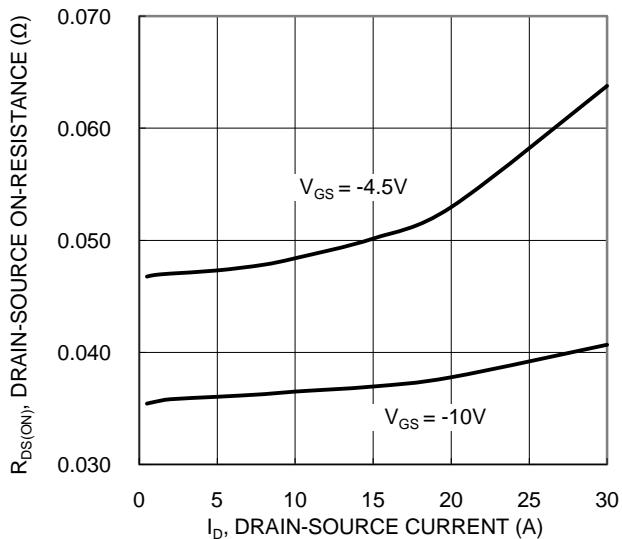


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

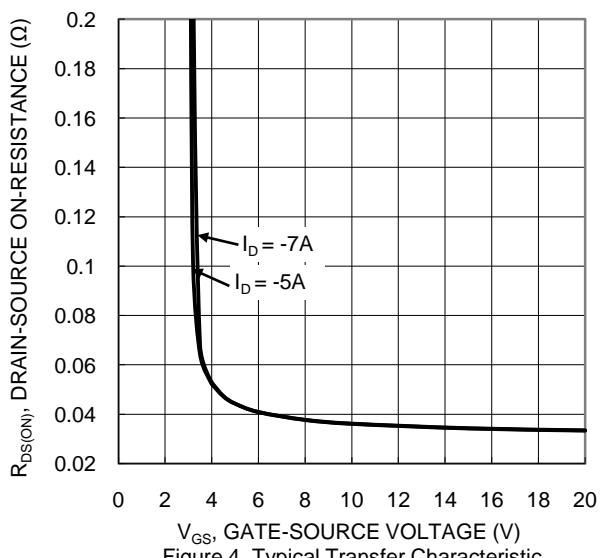


Figure 4. Typical Transfer Characteristic

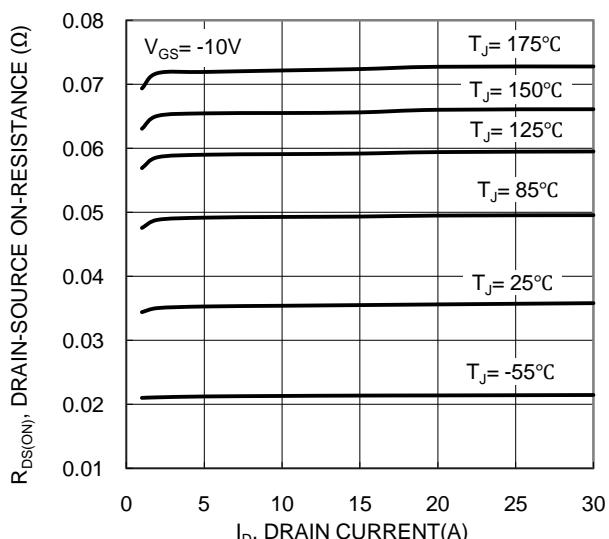


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

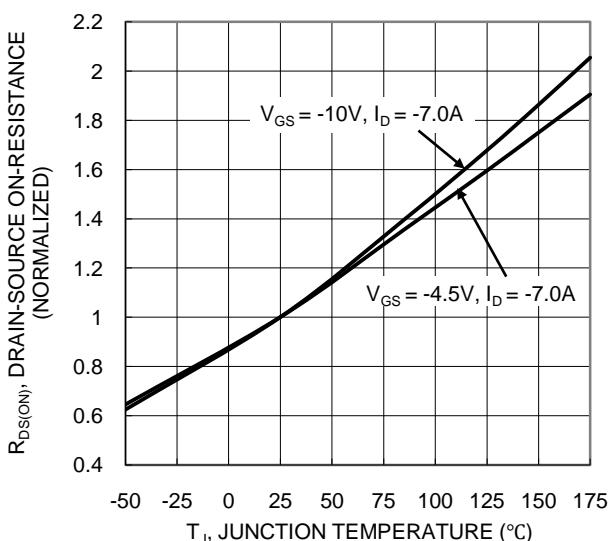
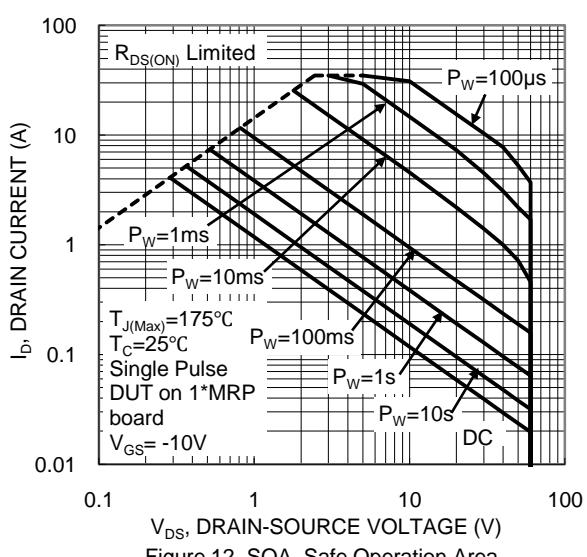
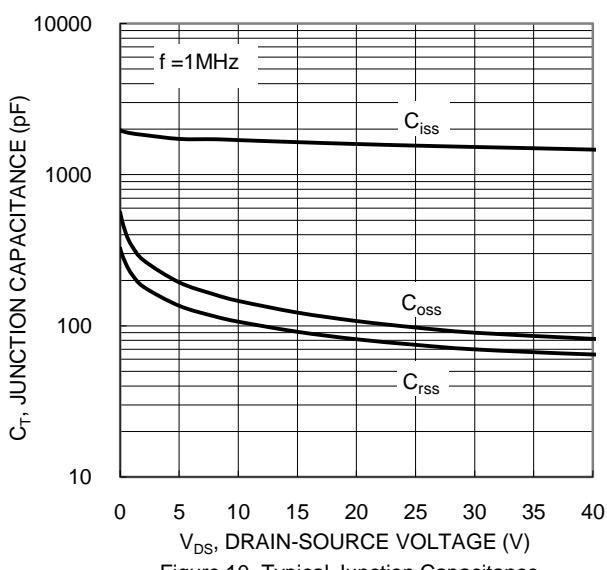
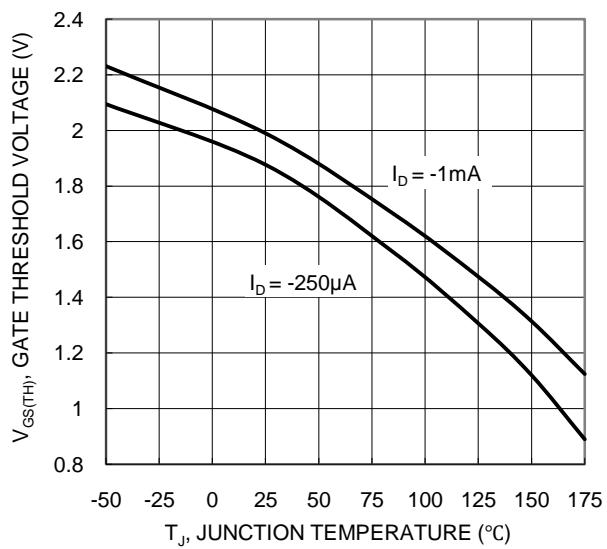
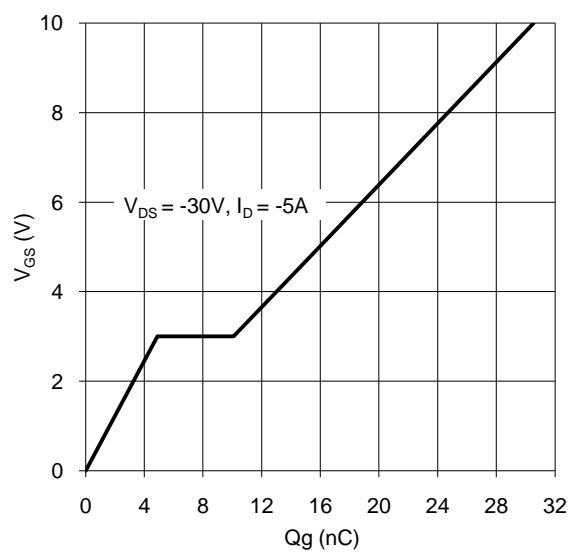
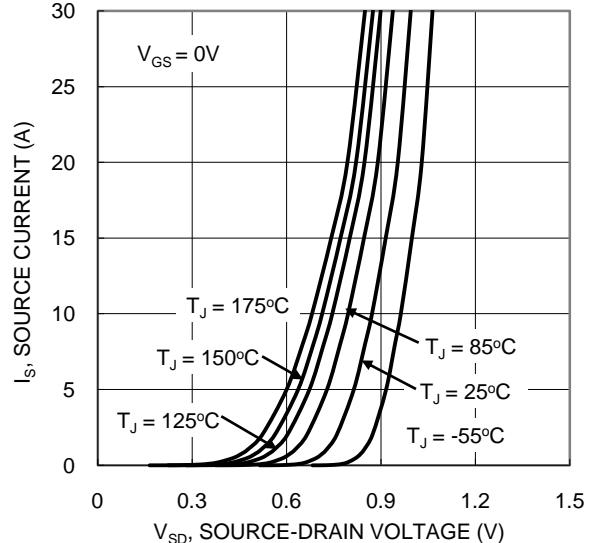
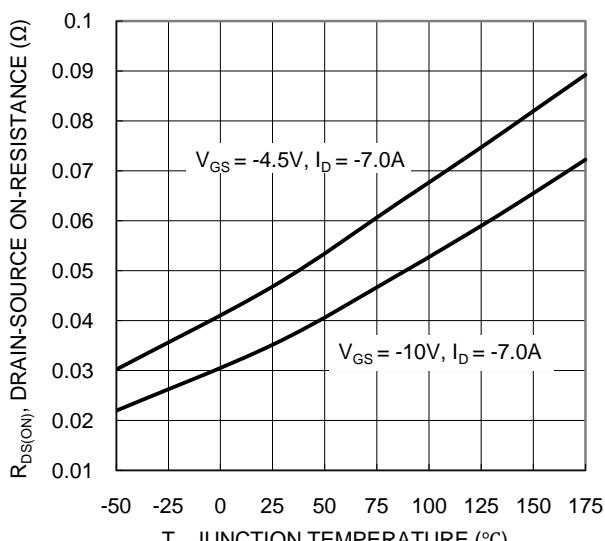


Figure 6. On-Resistance Variation with Temperature



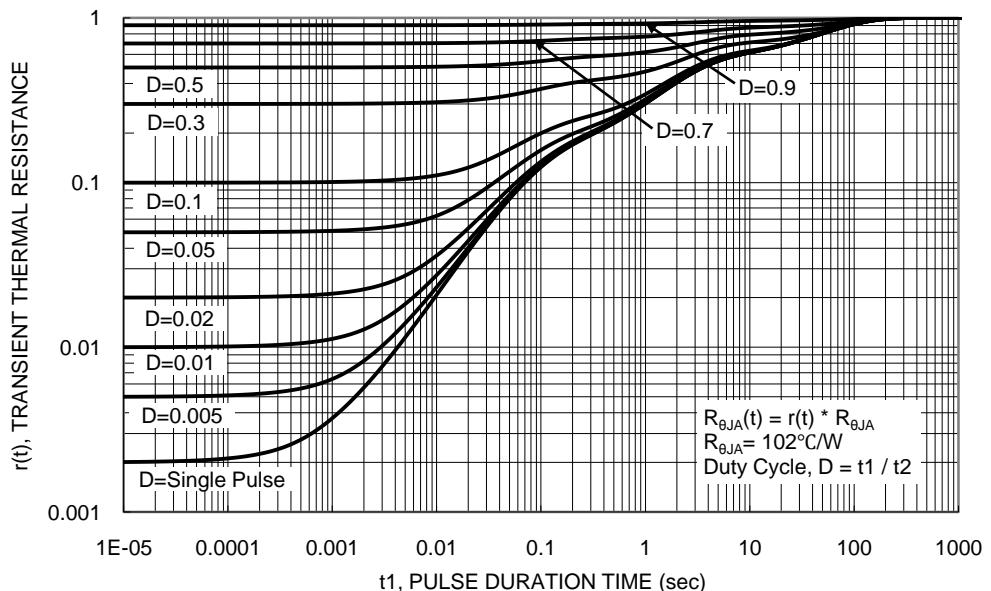
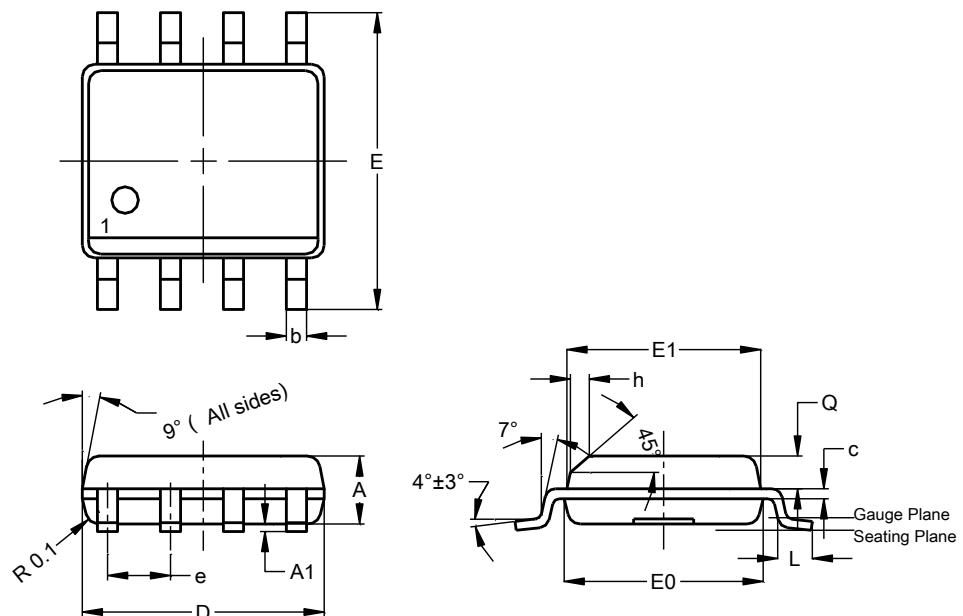


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



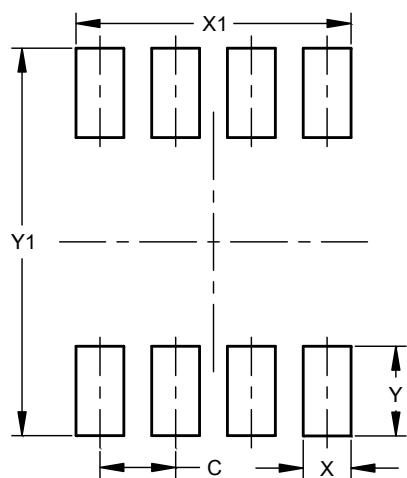
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Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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